

ABSTRACT OF THE DISCLOSURE

An optical semiconductor element (14) of the cap sealing type is aligned with an optical axis of an optical part contained in a resin housing (12), and mounted on the resin housing. In this case, the upper surface of a cap of the optical semiconductor element is butted to the end face of the housing, and bonded to the latter (by ultraviolet curing adhesive 20). In the optical module body having such a structure, the surface of the cap of the optical semiconductor element and at least a part of the side surface of the housing may be covered with a casing, and a clearance formed therebetween may be sealed with resin.